

patterning the middle layer using said one or a stack of layers as a photomask, wherein said middle layer is exposed to light passed through the ~~groves~~ grooves in the one or a stack of layers; and

developing said middle layer to form ~~longitudinally~~ spaced apart ridges in the said middle layer disposed in the ~~groves~~ grooves in said one or a stack of layers, said ridges forming a support structure which is part of the microelectromechanical systems device.

2. (Original) The method of claim 1, wherein the substrate permits light to pass therethrough.
3. (Original) The method of claim 2, wherein the substrate comprises glass.
6. (Previously Presented) The method of claim 1, further comprising depositing a top layer over said middle layer.
7. (Original) The method of claim 1, wherein said one or an uppermost layer of said stack of layers is a sacrificial layer.
8. (Original) The method of claim 1, wherein the said middle layer comprises a negative-acting-photosensitive material.
9. (Original) The method of claim 6, wherein said top layer comprises nickel and aluminum.

10. (Original) The method of claim 6, further comprising patterning said top layer.
12. (Currently Amended) The method of claim 10, wherein said top layer is patterned to define transversely extending strips which are supported by the ~~longitudinally~~ spaced apart ridges in the said middle layer.
13. (Currently Amended) A method for fabricating a microelectromechanical systems device, the method comprising:
- a) depositing one or a stack of layers on a base layer, said one layer or an uppermost layer in said stack of layers being a sacrificial layer;
 - b) patterning said one or a stack of layers to provide at least one aperture therethrough through which said base layer is exposed;
 - c) depositing a photosensitive layer over said one or a stack of layers; ~~and~~
 - d) passing light through said at least one aperture to expose said photosensitive layer; ~~and~~
 - e) developing said one or a stack of layers to remove unexposed portions of said photosensitive layer and said sacrificial layer to form at least one mechanical support, each support being defined by a portion of said photosensitive layer exposed through an aperture[.]; ~~and~~
 - f) removing said sacrificial layer to form at least one mechanical support, each support being defined by a portion of said photosensitive layer exposed through an aperture.
14. (Original) The method of claim 13, wherein the base layer is a substrate layer.

15. (Original) The method of claim 13, wherein said light comprises ultraviolet light.
16. (Original) The method of claim 13, wherein said photosensitive layer comprises a negative-acting-photosensitive material.
17. (Original) The method of claim 13, further comprising depositing a structural layer over said photosensitive layer.
19. (Previously Presented) The method of claim 17, wherein said steps (a) to (e) are repeated at least once, wherein for each repetition, the structural layer forms the base layer.